

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/05/2022

Details for "SN74AHCT14QPWRQ1"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
SN74AHCT14QPWRQ1	NIPDAU	Level-1-260C-UNLIM	TI MALAYSIA A/T	PW 14	4.4x5x1.15	57.6

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.00001	0.000671	7	0.000002	0
Precious Metals	Gold	7440-57-5	0.148927	99.997986	999980	0.258511	2585
Precious Metals	Silver	7440-22-4	0.000002	0.001343	13	0.000003	0
Sub-Total			0.14893	100	1000000	0.258516	2585
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.084948	70.000165	700002	0.147454	1475
Thermoplastics	Epoxy	85954-11-6	0.036406	29.999835	299998	0.063194	632
Sub-Total			0.121354	100	1000000	0.210649	2106
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	21.33279	97.41	974100	37.029891	370299
Copper and Its Alloys	Iron	7439-89-6	0.5256	2.4	24000	0.912347	9123
Copper and Its Alloys	Phosphorus	7723-14-0	0.00657	0.03	300	0.011404	114
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00657	0.03	300	0.011404	114
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.00657	0.03	300	0.011404	114
Zinc and Its Alloys	Zinc	7440-66-6	0.0219	0.1	1000	0.038014	380
Sub-Total			21.9	100	1000000	38.014466	380145
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.370968	95.12	951200	0.643934	6439
Precious Metals	Gold	7440-57-5	0.003042	0.78	7800	0.00528	53
Precious Metals	Palladium	7440-05-3	0.01599	4.1	41000	0.027756	278
Sub-Total			0.39	100	1000000	0.67697	6770
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	29.537065	85.500002	855000	51.271039	512710
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	1.036388	2.999999	30000	1.798983	17990
Other Organic Materials	Chlorine	7782-50-5	0.006909	0.019999	200	0.011993	120
Other Plastics and Rubber	Carbon Black	1333-86-4	0.103639	0.300001	3000	0.179899	1799
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.034546	0.099999	1000	0.059966	600
Thermoplastics	Epoxy	85954-11-6	3.827727	11.08	110800	6.644246	66442
Sub-Total			34.546274	100	1000000	59.966126	599661
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.50309	100	1000000	0.873274	8733
Sub-Total			0.50309	100	1000000	0.873274	8733
Total			57.609648			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.